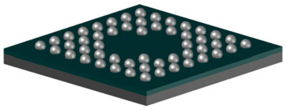
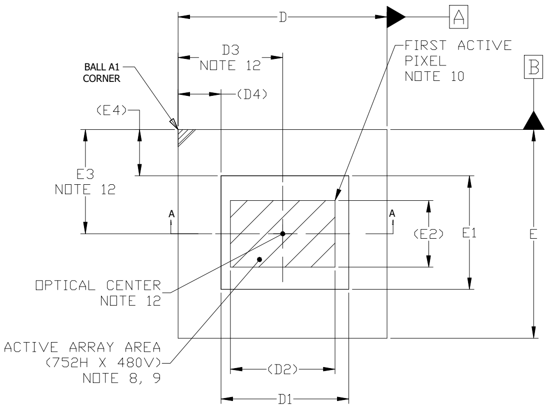


IBGA52 9x9x1.44, 1.00P
CASE 503AA
ISSUE C

DATE 19 MAY 2023

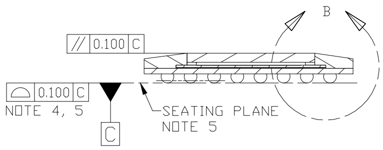


TOP VIEW

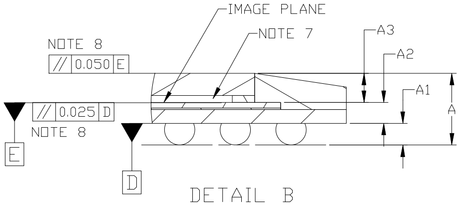
NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS [mm].
3. SOLDER BALL DIAMETER IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
6. GLASS: 0.400 THICKNESS; REFRACTIVE INDEX = 1.52; AR COATING R<1% 420-850nm (EACH SIDE).
7. AIR GAP BETWEEN GLASS AND PIXEL ARRAY: 0.125 THICKNESS.
8. PARALLELISM APPLIES ONLY TO THE ACTIVE ARRAY.
9. MAXIMUM ROTATION OF ACTIVE ARRAY RELATIVE TO DATUMS A AND B IS ±1.0°.
10. REFER TO THE DEVICE DATA SHEET FOR TOTAL PIXEL ARRAY DEFINITIONS.
11. PACKAGE CENTER (X, Y) = (0.000, 0.000).
12. OPTICAL CENTER RELATIVE TO PACKAGE CENTER (X, Y) = (0.000, 0.000).

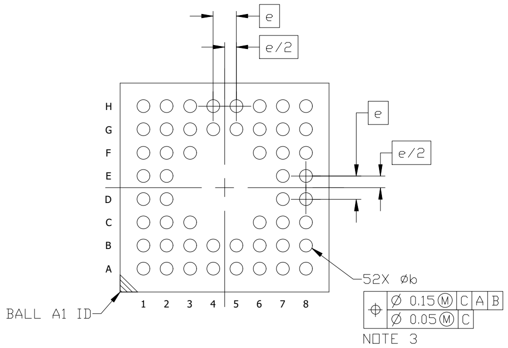
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	~	~	1.440
A1	0.340	0.390	0.440
A2	0.325	0.375	0.425
A3	0.475	0.525	0.575
b	0.450	0.500	0.550
D	8.925	9.000	9.075
D1	5.400	5.500	5.600
D2	4.512 REF.		
D3	4.425	4.500	4.575
D4	1.849 REF.		
E	8.925	9.000	9.075
E1	4.800	4.900	5.000
E2	2.880 REF.		
E3	4.425	4.500	4.575
E4	1.999 REF.		
e	1.000 BSC.		



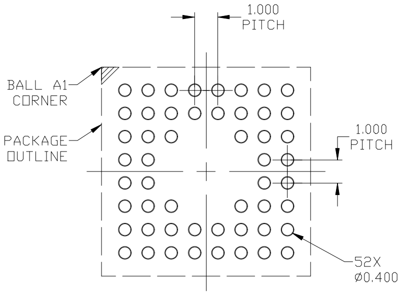
SECTION A-A



DETAIL B
SCALE 2:1



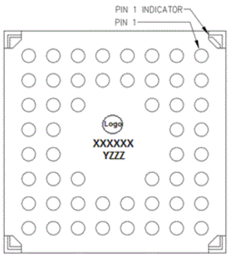
BOTTOM VIEW



RECOMMENDED MOUNTING FOOTPRINT*

* FOR ADDITIONAL INFORMATION ON OUR Pb-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
Y = Year
ZZZ = Lot Traceability

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

DOCUMENT NUMBER:	**98AON93388F**	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped “CONTROLLED COPY” in red.
DESCRIPTION:	**IBGA52 9x9x1.44, 1.00P**	**PAGE 1 OF 1**